

ABSTRACT OF THE DISCLOSURE

In a laser beam machining method for a wiring board, a  
5 machined portion of the wiring board is irradiated with a  
pulsed laser beam for a beam irradiation time ranging from  
about 10 to about 200  $\mu$ s and with energy density of about 20  
J/cm<sup>2</sup> or more, thereby machining the wiring board, for  
10 example, drilling for a through-hole and a blind via hole,  
grooving, and cutting for an outside shape.

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